

Technical Data Sheet

AutoRTV Silicone Gasket High Temp

PRODUCT DESCRIPTION

Bondloc Silicone Gasket is a high temperature, single component, high modulus, acetoxy curing silicone sealant / adhesive that vulcanises at room temperature to provide a permanently flexible seal and bond. Joint movements of up $\pm 30\%$. Temperatures resistance 300°C continuously / 342°C intermittently.

APPLICATIONS

Adheres to most services. Easy to use. Bondloc Silicone Gasket can be used in home, automotive & marine applications. It is weatherproof and water resistant. It adheres to a variety of materials including glass, vinyl, wood, brick & concrete. It is good for sealing aluminium and metal flanges on gearboxes. Can be used in fabrications, butt and channel glazing, refrigeration and hygiene seal, aluminium gutter sealing, most industrial applications.

USEFUL NOTES

- Joint movements of up to ±30%
- Temperature resistance 300°C continuously 342°C intermittently
- · Adheres to most surfaces
- Easy to use

INSTRUCTIONS FOR USE

Surface Preparation: Joint must be sound, clean, dry and free from oil and greases. Use B7063 cleaner or a strong gasket remover

Power Can: Remove end cap, break away small grey clip, trigger becomes active, indicator shows direction to turn to increase and decrease flow. Dispense bead as required. Cartridge: Cut the tip of the cartridge taking care not to damage the thread and affix nozzle to cartridge. Cut nozzle at 45° leaving an opening slightly larger than the gap to be filled. Apply using a standard sealant gun using firm even pressure to achieve the desired bead width. To ensure a proper bond smooth the sealant with a spatula or similar tool

Cleaning: Clean up any excess material immediately with white spirit. Hardened sealant can only be removed mechanically or with sealant remover. Wash hands with soap and water.

STORAGE

Store in a cool area out of direct sunlight in unopened containers away from sources of heat.

TECHNICAL FEATURES

Chemical Base	100% Silicone Polymer
Solids Content	100%
Appearance	Black/Red Viscous Paste
Shrinkage	None
Specific Gravity	1.04
Skinning Time	5 minutes @ 20°C
Full Cure	3mm per day @25°C @50%rH
Cleaning Solvent	White Spirit
Application Temperature	+5 to +60°C

TYPICAL BOND/SEAL CHARACTERISTICS

Movement	± 30%
Accommodation	
Temperature Resistance	-50°C to 300°C
Hardness Shore A	25-30
Elongation at Break	450%

RECOMMENDATION FOR JOINTS

Minimum Joint	4mm
Maximum Joint Depth	30mm
	Max. Depth 50% of joint width
	10 linear meters (9mm x 9mm joint)

HEALTH & SAFETY

This technical information sheet does not constitute a Safety Data Sheet (SDS). Before using this product ensure you have read and fully understood this products SDS.

PACKAGING FORMAT

100ml, 200ml (power can), 310ml

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PRECAUTIONS: This product and the auxiliary materials normally combined with it are capable of producing adverse health effects ranging from minor skin irritation to serious systemic effects. None of these materials should be used, stored, or transported until the handling precautions and recommendations as stated in the Safety Data Sheets (SDS) for this and all other products being used are understood by all persons who will work with the product. Warranty: All products purchased from or supplied by Bondloc are subject to terms and conditions set out in the contract. Bondloc warrants only that its product will meet those specifications designated as such herein or in other publications. All other information supplied by Bondloc is consider accurate but are furnished upon the express condition the ustomer shall make its own assessment to determine the product's suitability for a particular purpose. Bondloc makes no other warranty, either express or implied, including those regarding such other information, the data upon which the same is based, or the results to be obtained from the use thereof; that any product shall be metchantable or fit for any particular purpose; or that the use of such other information or product will not infringe any patent.

